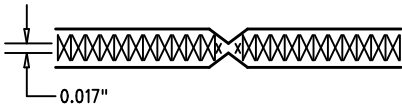


NOTES: Unless Otherwise Specified

- 1. MATERIAL: FR4 OR EQUIVALENT EPOXY
2 OZ. COPPER CLAD
THICKNESS .062" +/- .006
TOTAL OF 2 LAYERS
- 2. LOCATION OF ALL PATTERN HOLES TO BE PROGRAMMED
FROM GERBER FILES. TRUE CENTER POSITION WITHIN .003 MAX.
FINISHED SIZE FROM HOLE CHART WITH +/- .003".
- 3. BREAKOUT SPECIFICATION: ALL HOLES SHALL HAVE .003 MIN.
ANNULAR RING.
- 4. FINISH:
 - A. ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE.
 - B. ELECTRODEPOSITED TIN-LEAD COMPOSITION.
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC)
 - C. TOLERANCE:
 - REGISTER ALL LAYERS +/- .003"
 - ROUTING TOLERANCE +/- .005" OF FAB DRAWING DIMENSIONS.
 - D. SOLDER MASK: BOTH SIDES USING GREEN PC-401 OR EQUIVALENT.
 - E. SILKSCREEN: USING WHITE NON-CONDUCTIVE EPOXY INK.
- 5. REMOVE ALL SHARP EDGES AND BURRS.
- 6. PCB TO BE IN ACCORDANCE WITH IPC-A-600 STANDARDS
- 7. LAYER SEQUENCE: COMPONENT SIDE = LAYER1
SOLDER SIDE = LAYER2
- 8. SCORING:



Fabrication Drawing

SIZE	QTY	SYM	PLTD
25	6	Y	PLTD
95	5	Z	PLTD

